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Aim High *To Petascale... and Beyond!*

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Risk Factors

Today's presentations contain forward-looking statements. All statements made that are not historical facts are subject to a number of risks and uncertainties, and actual results may differ materially. Please refer to our most recent Earnings Release and our most recent Form 10-Q or 10-K filing available on our website for more information on the risk factors that could cause actual results to differ.

Definitions

High Performance Computing (HPC) - A collection of hardware systems, software tools, languages and generic programming approaches which make previously unfeasible applications possible and which is available at an appropriate price.

Peta Scale Computing – “(the) wide spread use of systems that deliver sustained applications performance a level above a PFlop/s.” - Horst D Simon, LBNL 8/24/2006

Supercomputing Datacenters Today

Supercomputers Solve Complex Problems

- 60% of US profits are in financial services
- As many as ten top tier firms with IT Budgets > \$2B/year
- Performance Needs:
 - 60,000 Transactions Per Second
 - 30ms average latency
 - 32GB real time database
- Good Scale out Application
 - Application is amenable to parallelization both data & thread
 - Requires Double Precision FP, high memory BW, ...

Sample Application: Collateralized Debt Obligation (CDO) Monte Carlo Simulation
400,000 underlying assets (400 branches, ~1,000 loans each)

Monte Carlo Simulation considers external factors and their interrelationships
400B scenarios (simplified).

- For each asset there are 1M paths. 1,000 prepay * 1,000 loss
- Future goal to compare CDO to another CDO deal (CDO^2) 160T scenarios ($400B^2$). Considering CDO^3

Wall Street:
Building 2-4 Data Centers Per Company by 2010

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Source: Intel

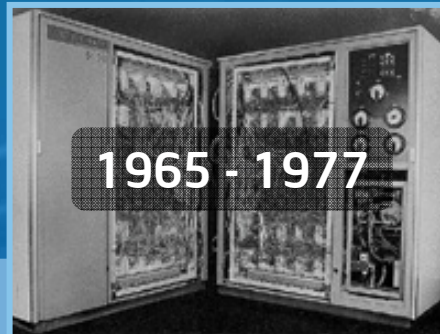


Yesterday, Today and Tomorrow in HPC

ENIAC
20 Numbers in Main Memory



CDC 6600 - First successful
Supercomputer 9MFlops

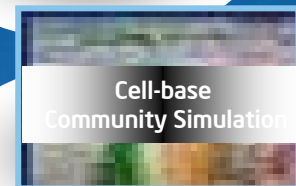
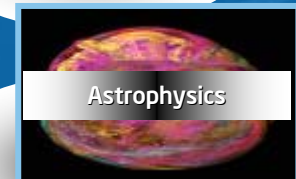


ASCI Red
(word fastest on top500 till 2000)
First Teraflop Computer,
9298 Intel Pentium® II Xeon Processors



Intel ENDEAVOR
464 Intel® Xeon® Processors 5100 series, 6.85
Teraflop MP Linpack, #68 on top500

~2008 Beyond



*PetaScale
Platforms*

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*Yesterday's Supercomputing
is Today's Personal Computing*

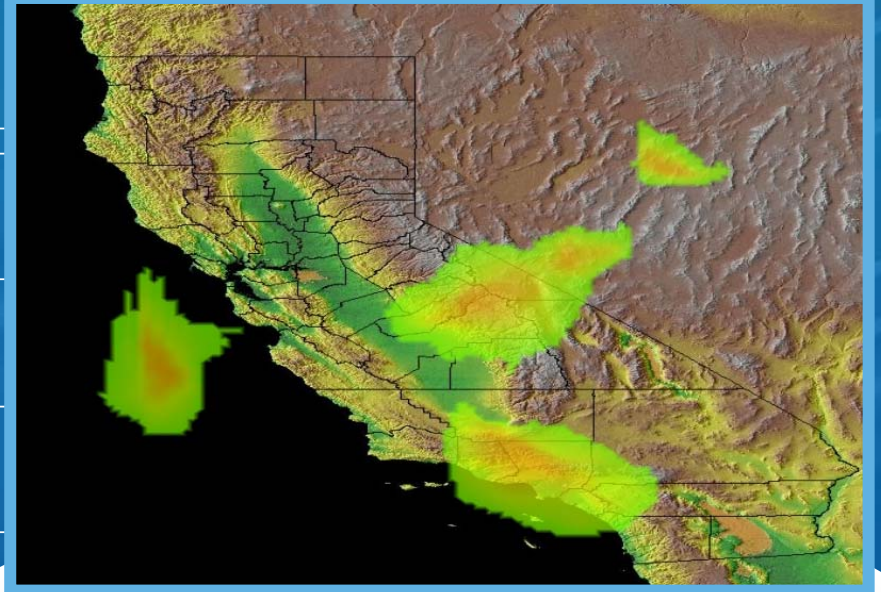
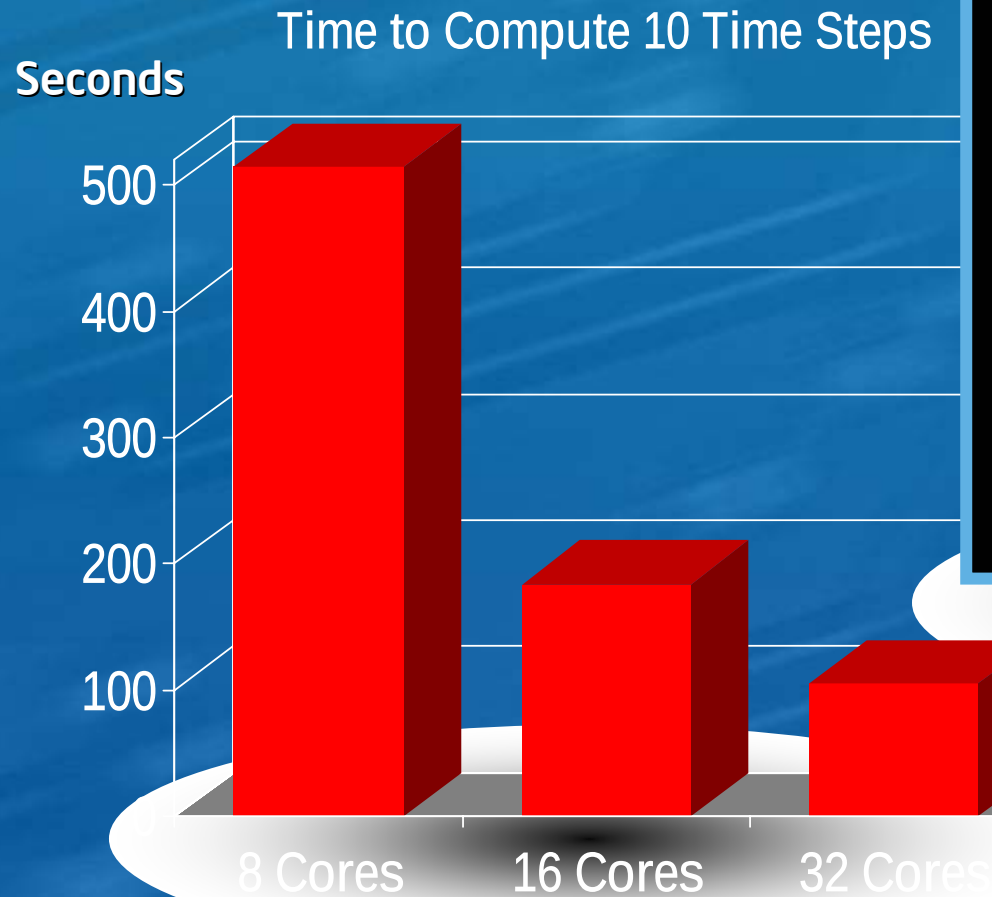




... together provide a powerful environment to rapidly develop solutions for computationally challenging problems

- Tyan* Personal Supercomputer
- Intel Quad-Core Xeon Processor
- Mellanox* High Performance InfiniBand Interconnect
- Microsoft* Windows Compute Cluster Server
- Wolfram* *gridMathematica* Supercomputing Environment

Performance Results



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Microsoft
Windows
Compute Cluster Server 2003

TYAN

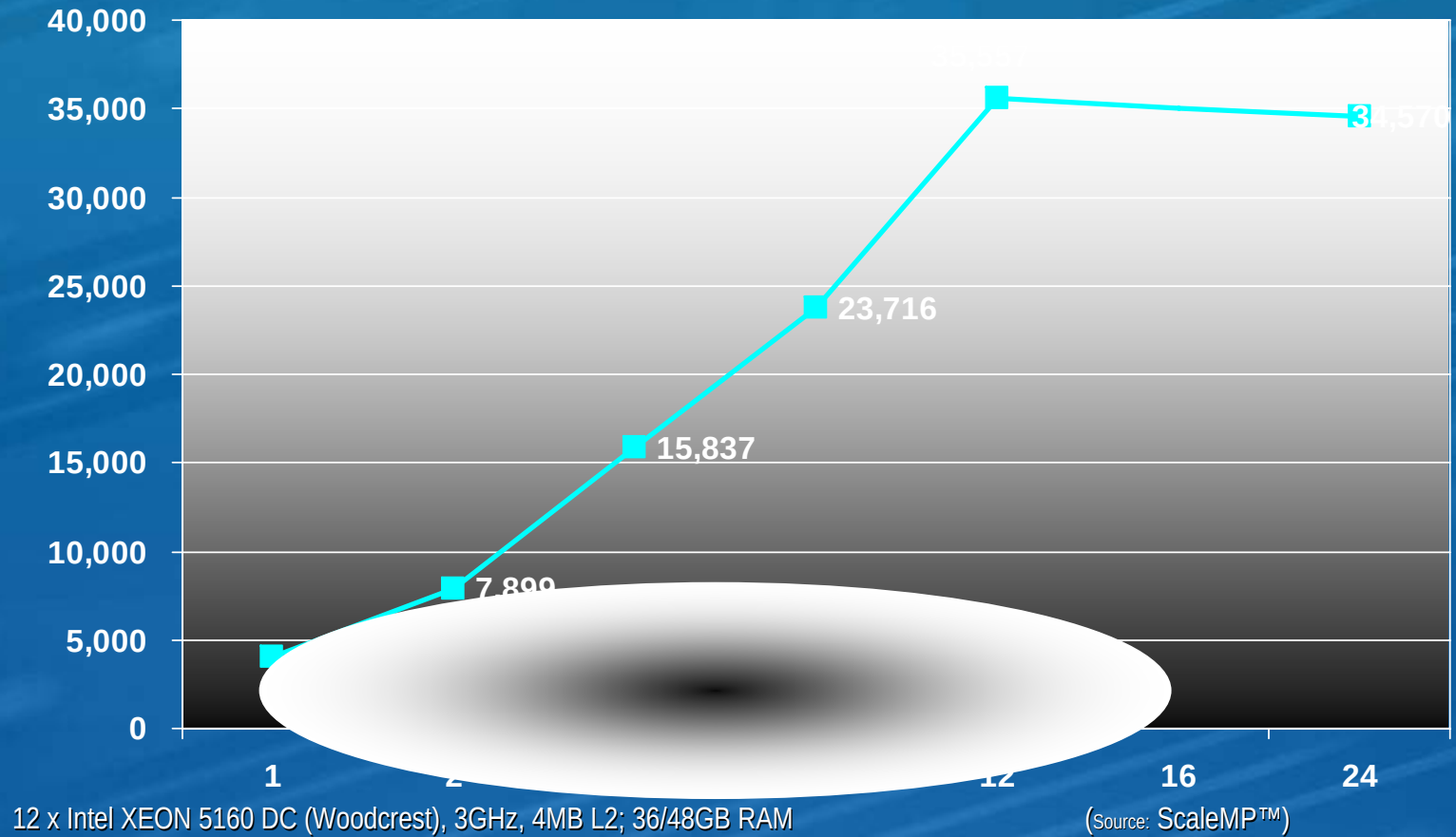
Mellanox
TECHNOLOGIES

WOLFRAMRESEARCH
MAKERS OF MATHEMATICA®

intel



Performance



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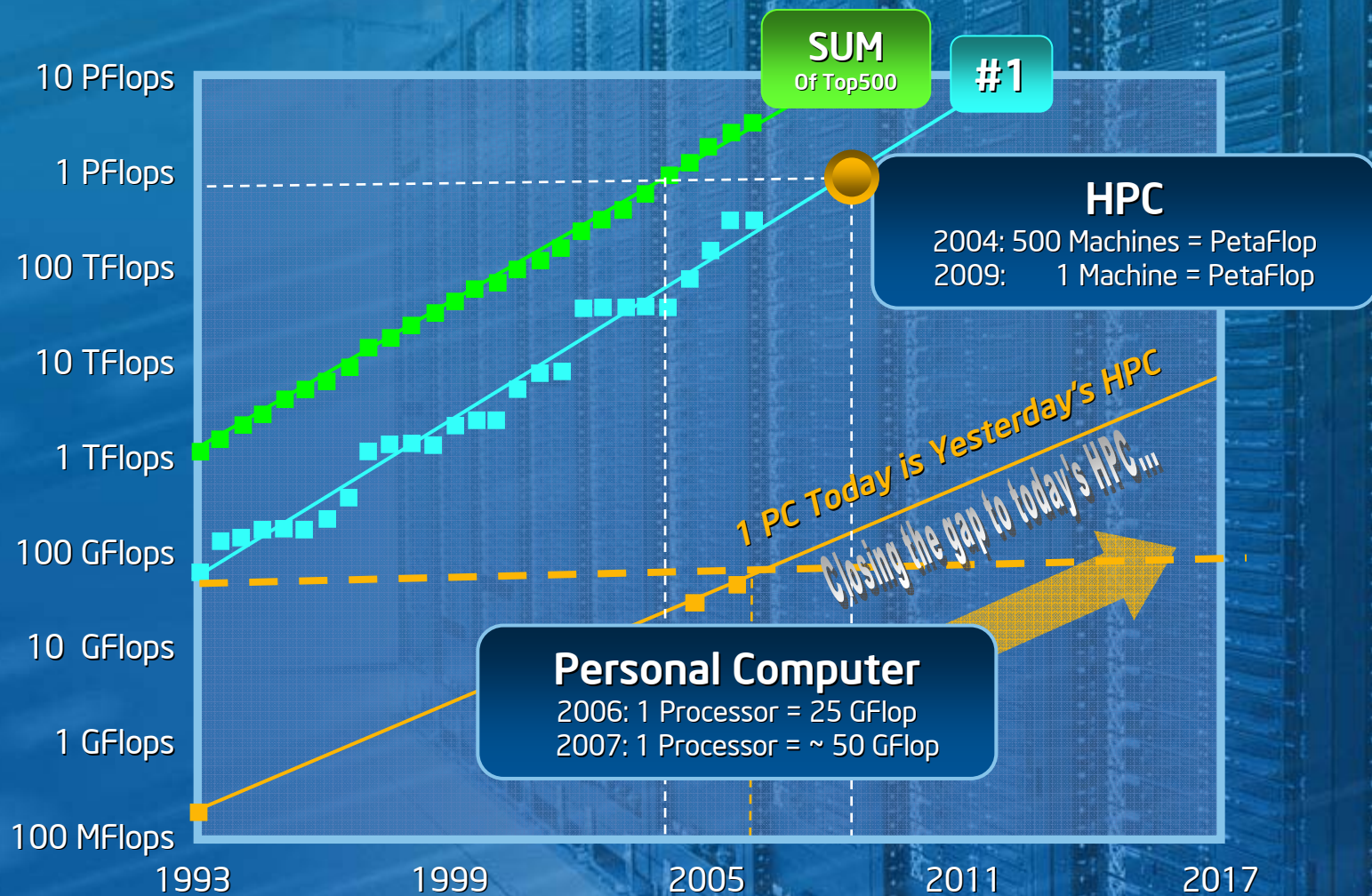
 CIARATECH

sg-i®

ScaleMP™



The Top500: Reaching Petascale



2008: Peak and Linpack PetaFlop – 2011: Sustained

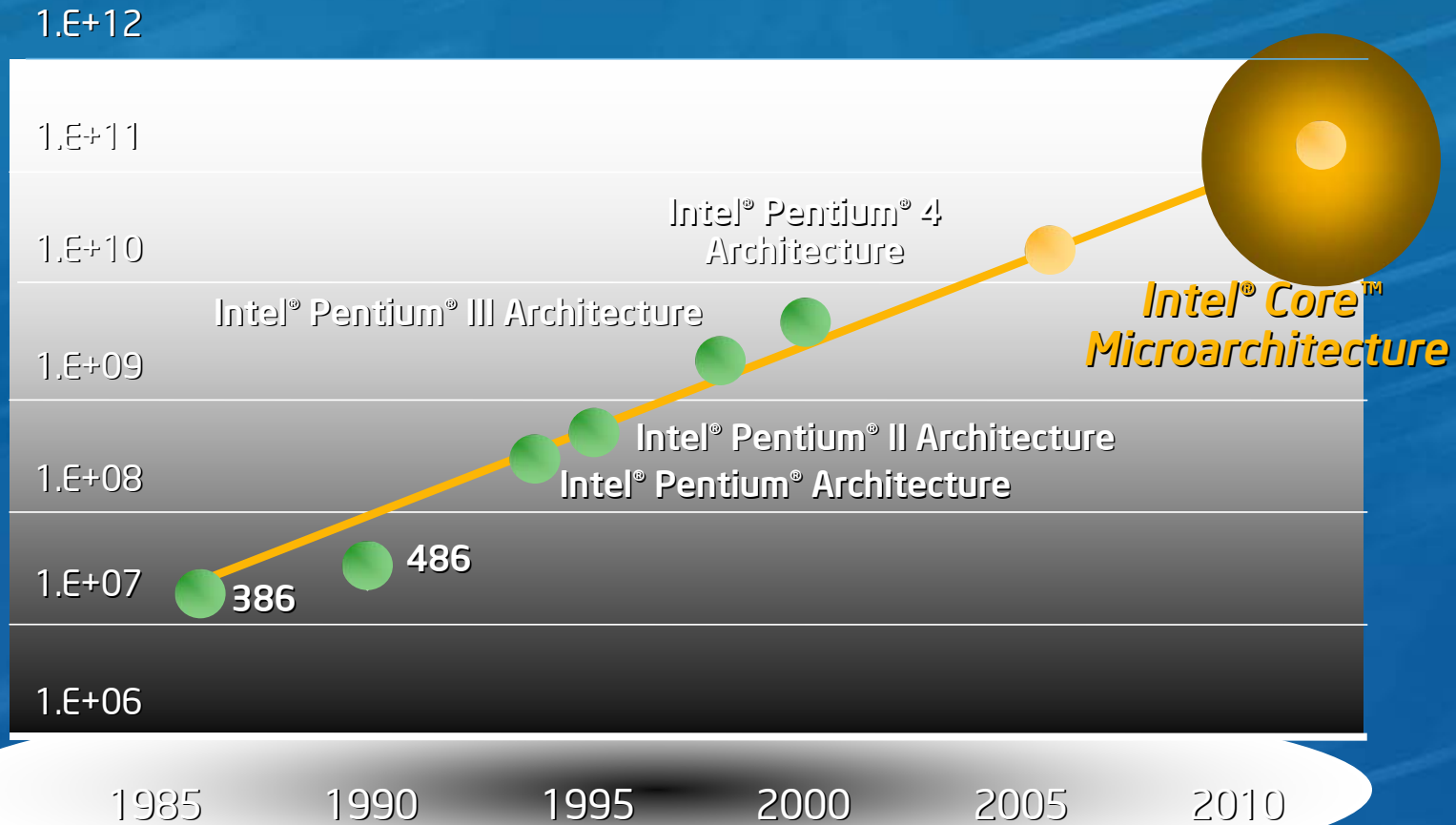
Source: HPC - www.top500.org, June 2006; PC - Intel

Let's Talk About ...
Challenges and Outlook
in Building a
Petascale Machine



Processor Performance

Flops



Reaching Petascale with ~100,000 Processors in 2010*

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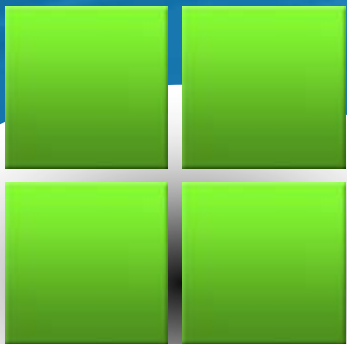
Assuming approx. 100Gflops processors

* Petascale assumes 10's of PF Peak Performance and 1PF Sustained Performance on HPC Applications.

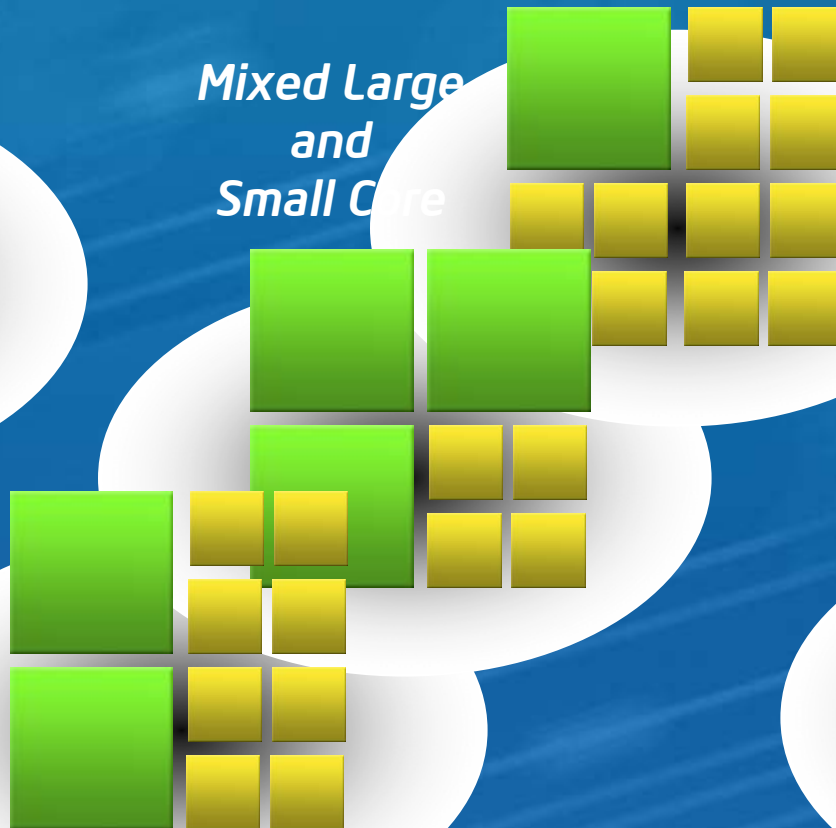


Multi-threaded Cores

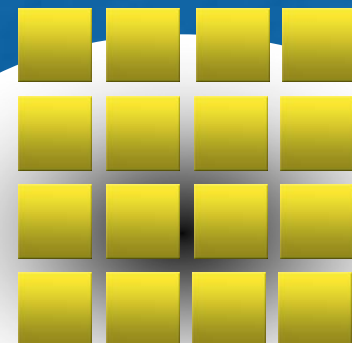
All Large Core



Mixed Large and Small Core



All Small Core

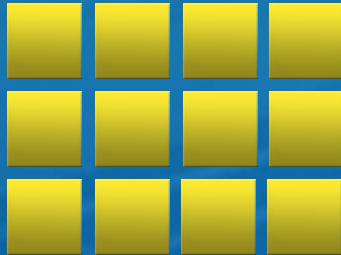


Energy Efficient Petascale with Multi-threaded Cores

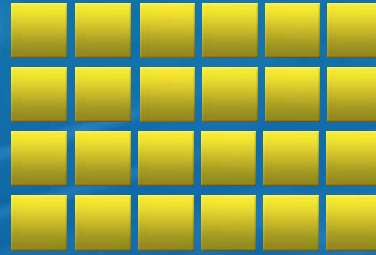
Increasing Throughput through Parallelism

Amdahl's Law: Parallel Speedup = $1 / (\text{Serial\%} + (1 - \text{Serial\%}) / N^)$*

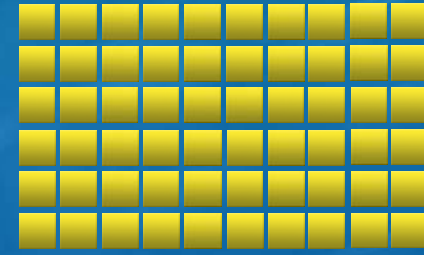
12 Cores



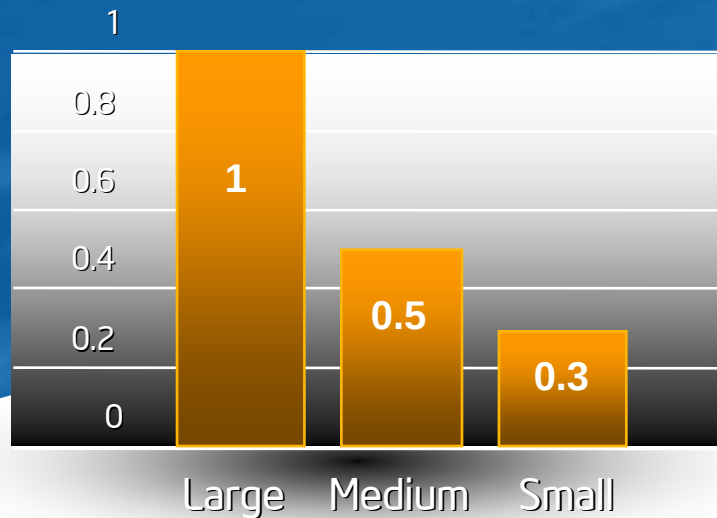
48 Cores



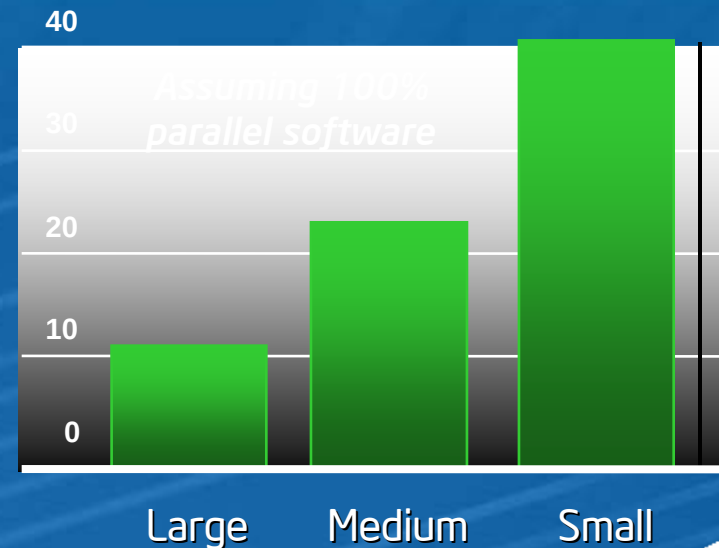
144 Cores



Single Core Performance
Relative Performance



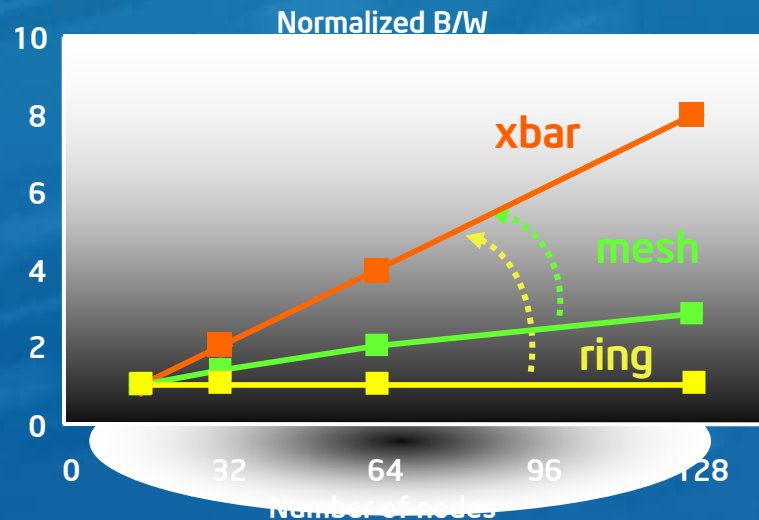
System Performance



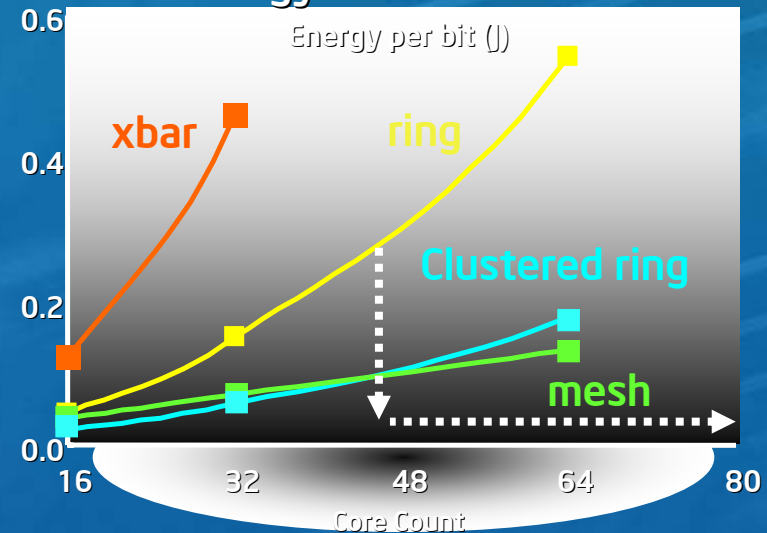
Inter-chip Interconnect Challenges

Bandwidth, Link Bandwidth and Power

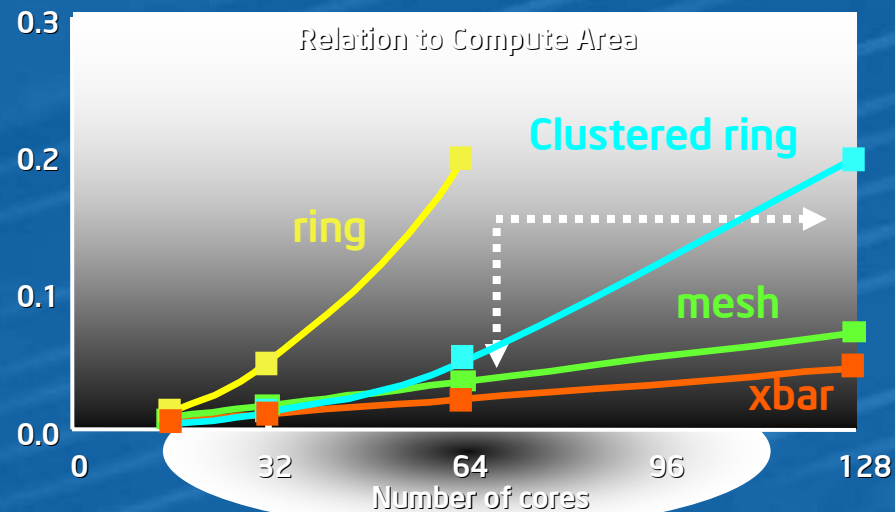
Topology Effect on Bandwidth



Energy Iso-Bandwidth



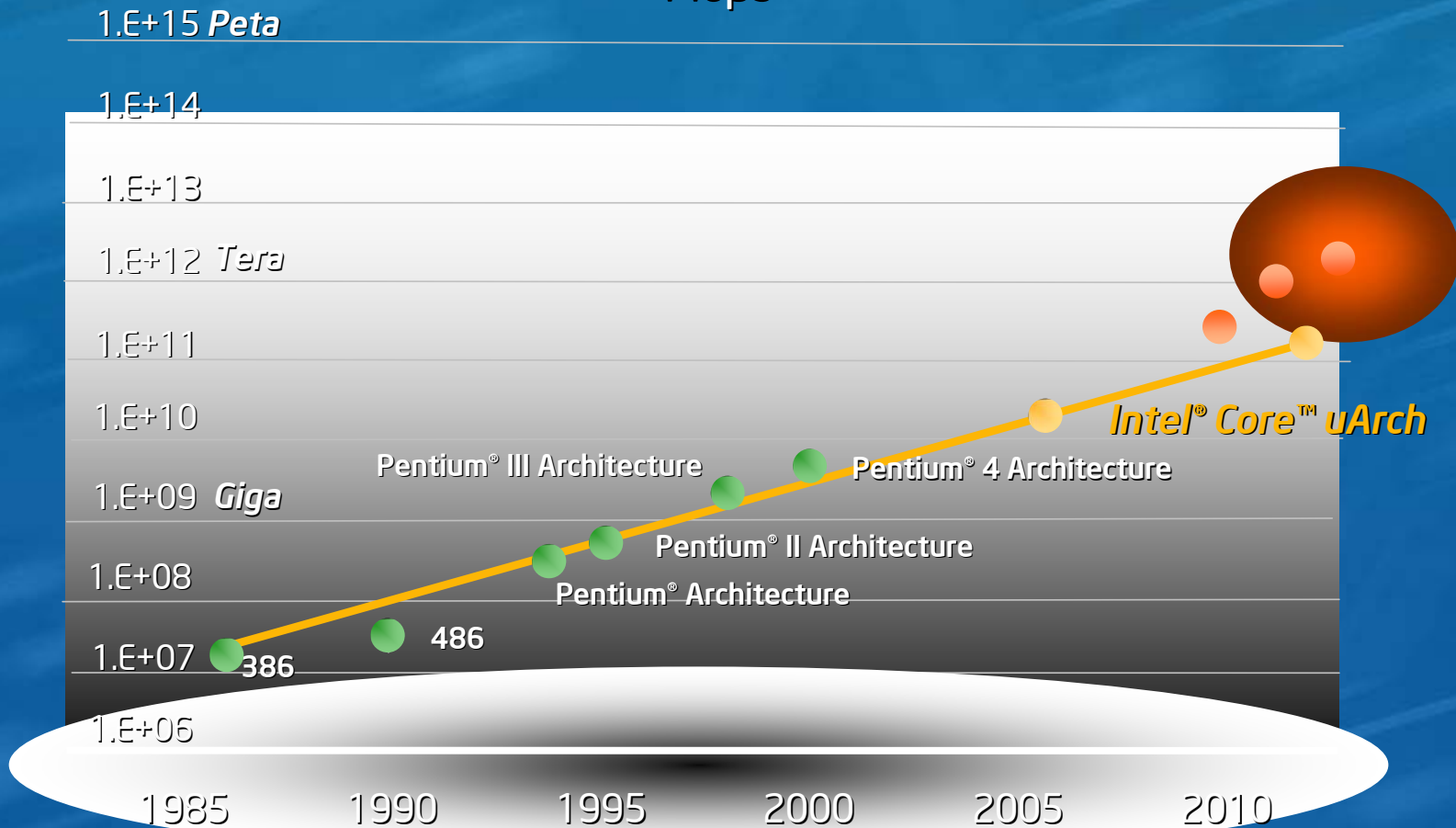
Interconnect Area Iso-Bandwidth



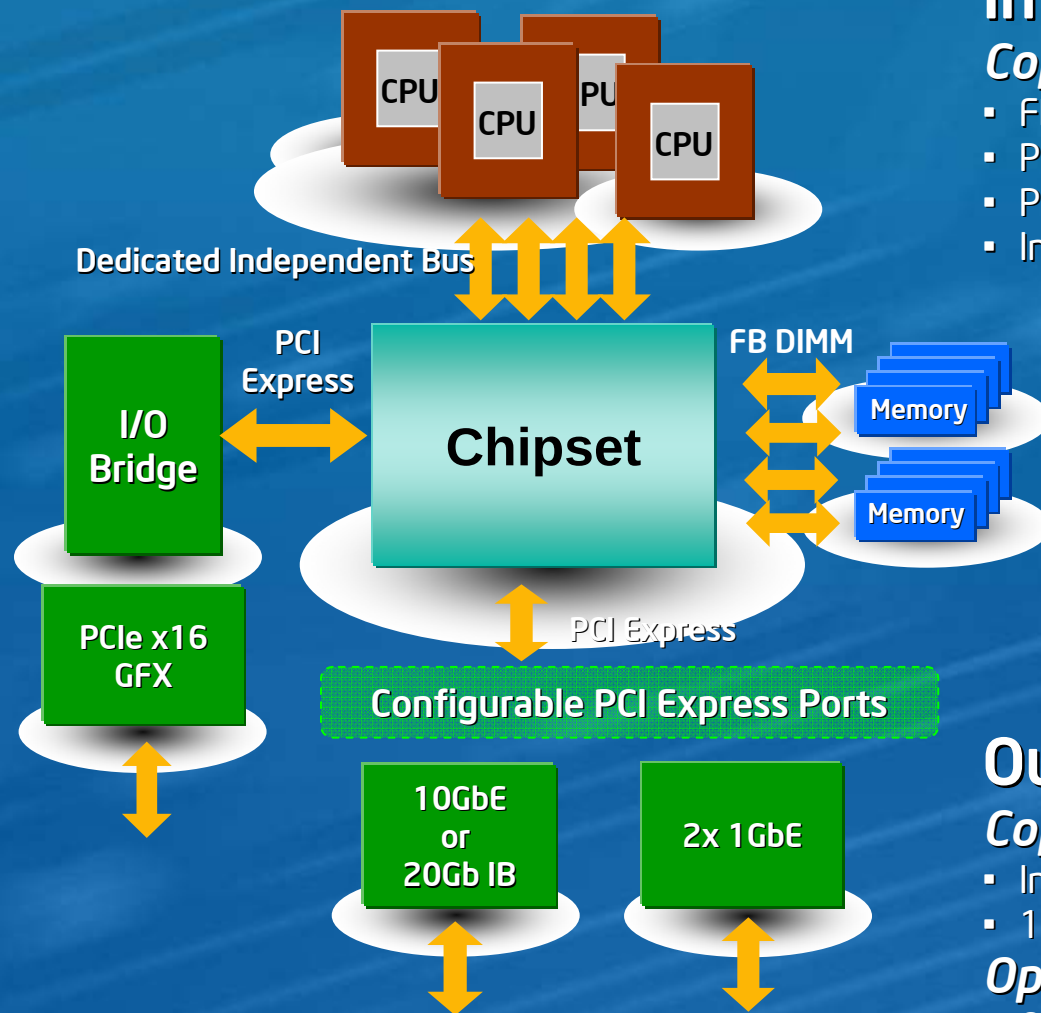
Increasing Processor Performance

Through Multi-threaded Cores

Flops



Inter-Chip Interconnect Performance Today



In the Box

Copper-based links:

- FB DIMM – 4GB/s per DIMM channel
- PCI express, gen. 1 – 2.5Gb/s
- PCI express, gen. 2 – 5Gb/s
- Intel Front-side Bus – 17GB/s



Out of the Box

Copper-based links:

- Infiniband DDR x4 – 20 Gb/s
- 1G Ethernet – 1Gb/s

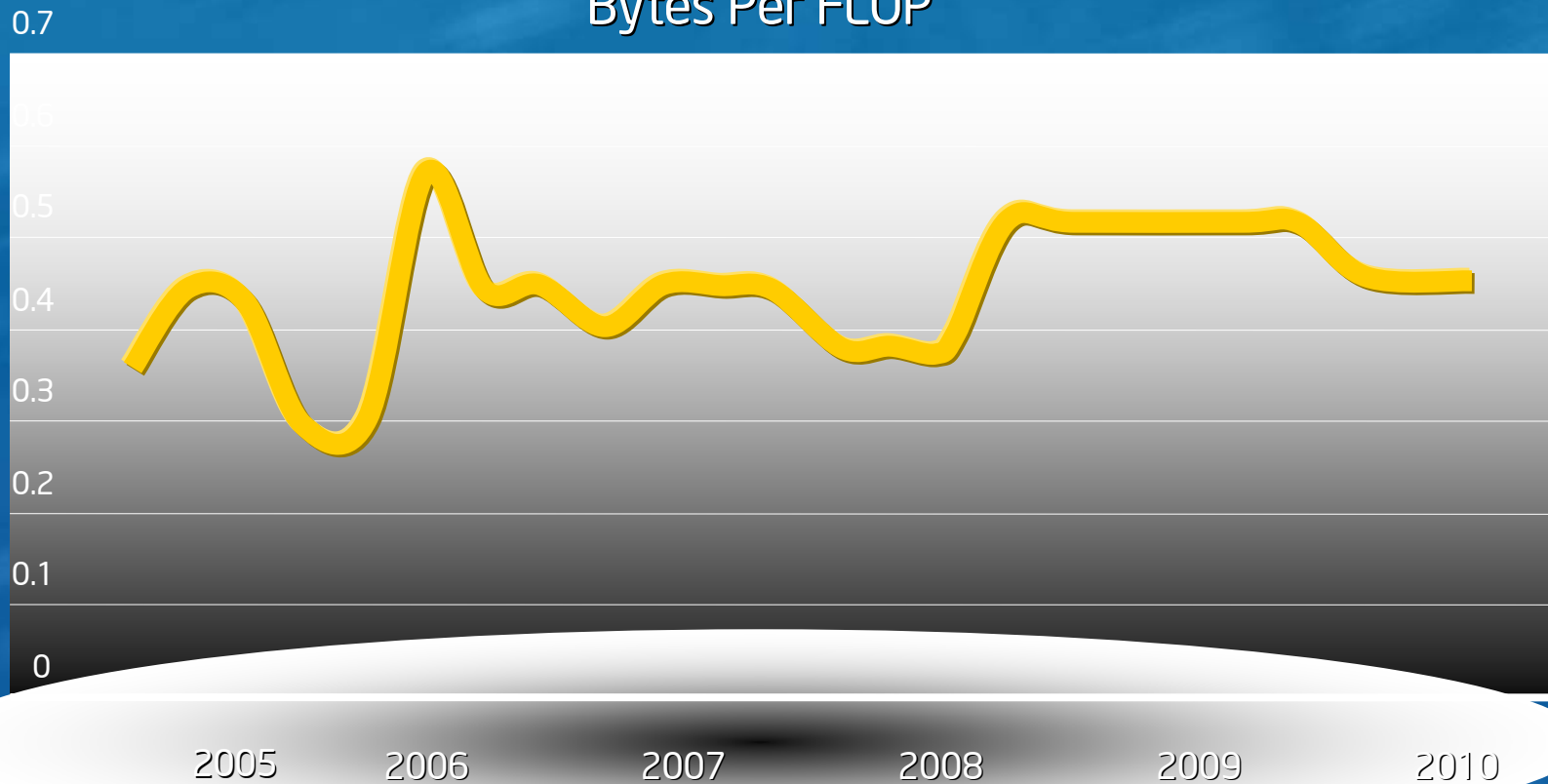
Optical-based links:

- OC-192 (long haul optical) – 10Gb/s
- 10G Ethernet – 10Gb/s

Memory Performance for Balanced Computing

Byte : Flop Ratio Has Been Consistent and Steady

Bytes Per FLOP



Continuing the Trend for Petascale Performance

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Source: Intel



Increasing Memory Bandwidth *to Keep Pace*

3D Memory Stacking

Power and IO Signals Go
Through DRAM to CPU

Thin DRAM Die

Through DRAM Vias

Heat-Sink

CPU

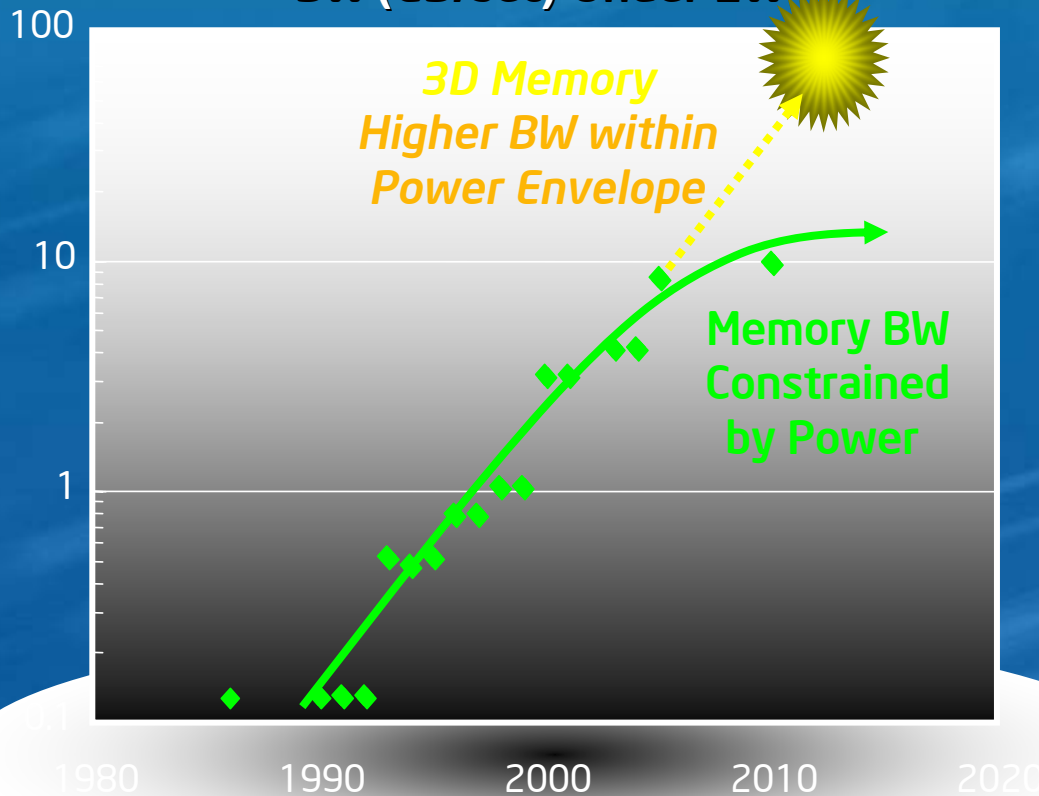
DRAM

Package

BW (GB/sec) Under 2W

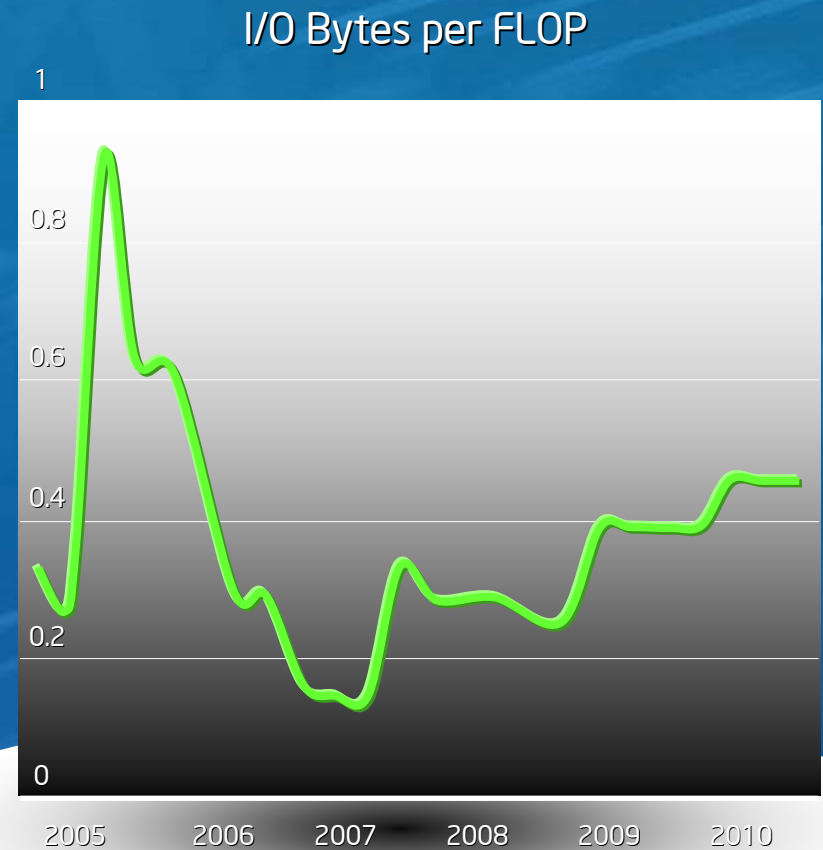
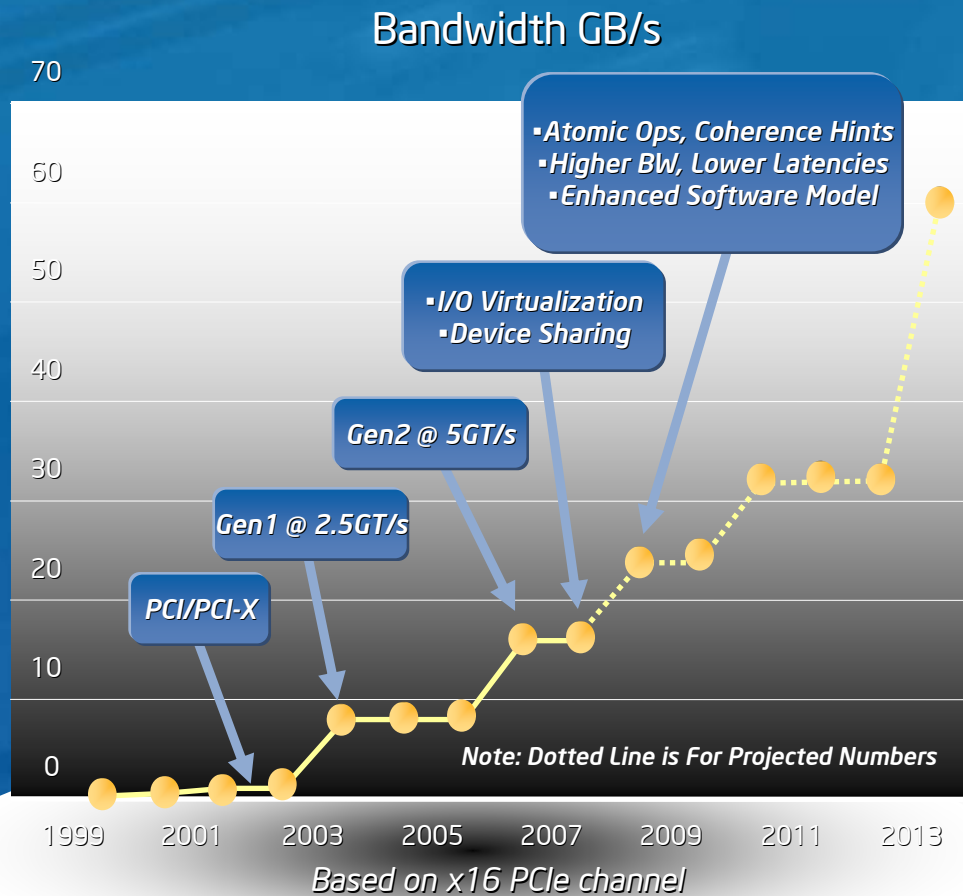
3D Memory
Higher BW within
Power Envelope

Memory BW
Constrained
by Power



PCI Express to Meet I/O Demand

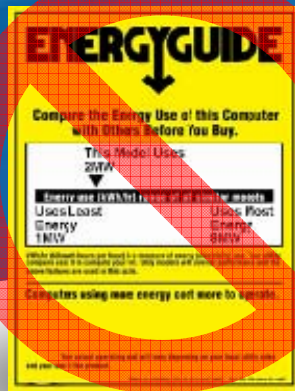
Performance, Bandwidth and Functionality



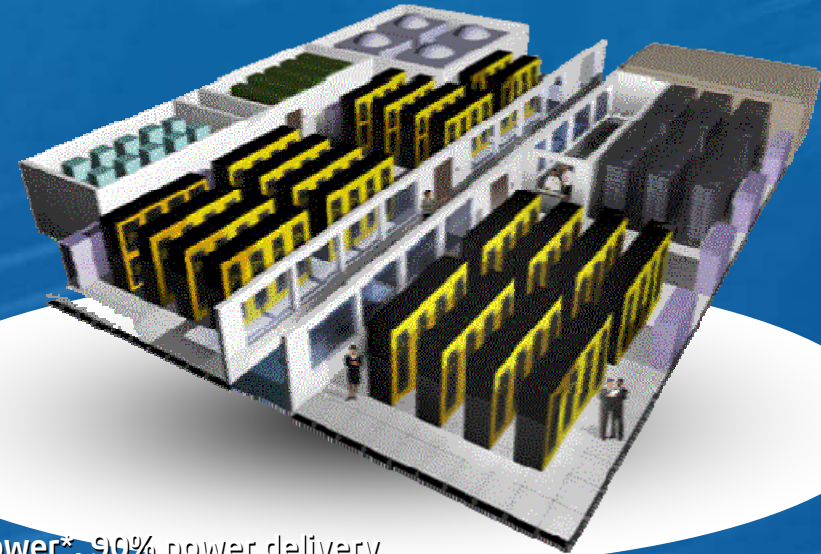
But ... How about
Power and Reliability

Power and Cooling Cost Today

$$\begin{array}{ccccccc} 10^{\text{¢}} & + & 9 & + & \text{Power} & = & \$14.6\text{M} \\ \text{Kilowatt} & & \text{Megawatt} & & \text{Delivery} & & \text{Electricity} \\ \text{Hour} & & \text{Datacenter} & & + & & \text{Costs/Year} \\ & & & & \text{Cooling} & & \end{array}$$



"DATACENTER ENERGY LABEL"



Assume: 9MW system power*, 90% power delivery efficiency, cooling Co-efficiency of Performance (COP)=1.5

*Source: HPC Wire "A Petaflop Before its Time," June 28, 2006

Managing Power and Cooling Efficiency



Silicon:

Moore's law, Strained silicon, Transistor leakage control techniques, Clock gating

Processor:

Policy-based power allocation
Multi-threaded cores

System Power Delivery:

Fine grain power management,
Ultra fine grain power management

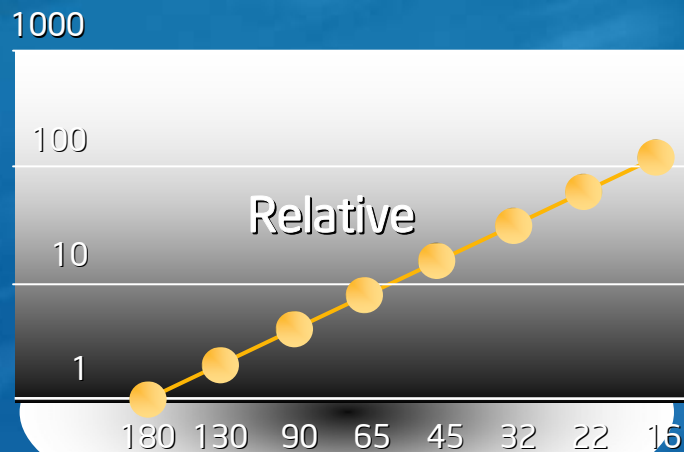
Facilities:

Air cooling and liquid cooling options
Vertical integration of cooling solutions

Reliability Challenge

Billions of Transistors

Soft Error FIT/Chip (Logic & Mem)

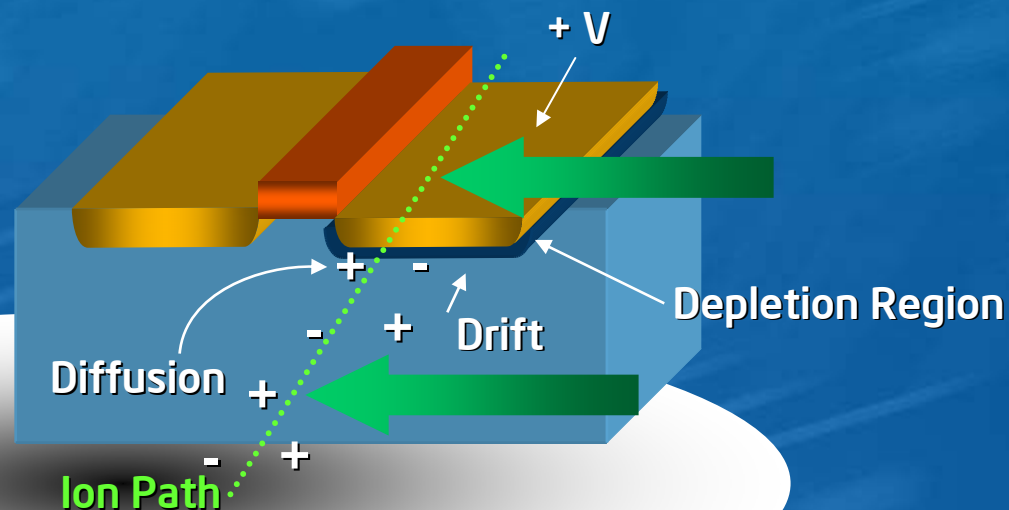


Assume: Chip size stays roughly the same with each generation.

Soft Errors or Single Event Upsets (SEU) are caused by charge collection following an energetic particle strike.

- **FIT/bit (mem cell):** expected to be roughly constant
- **Moore's law:** increasing the bit count exponentially: 2x every 2 years

An exponential growth in FIT/chip

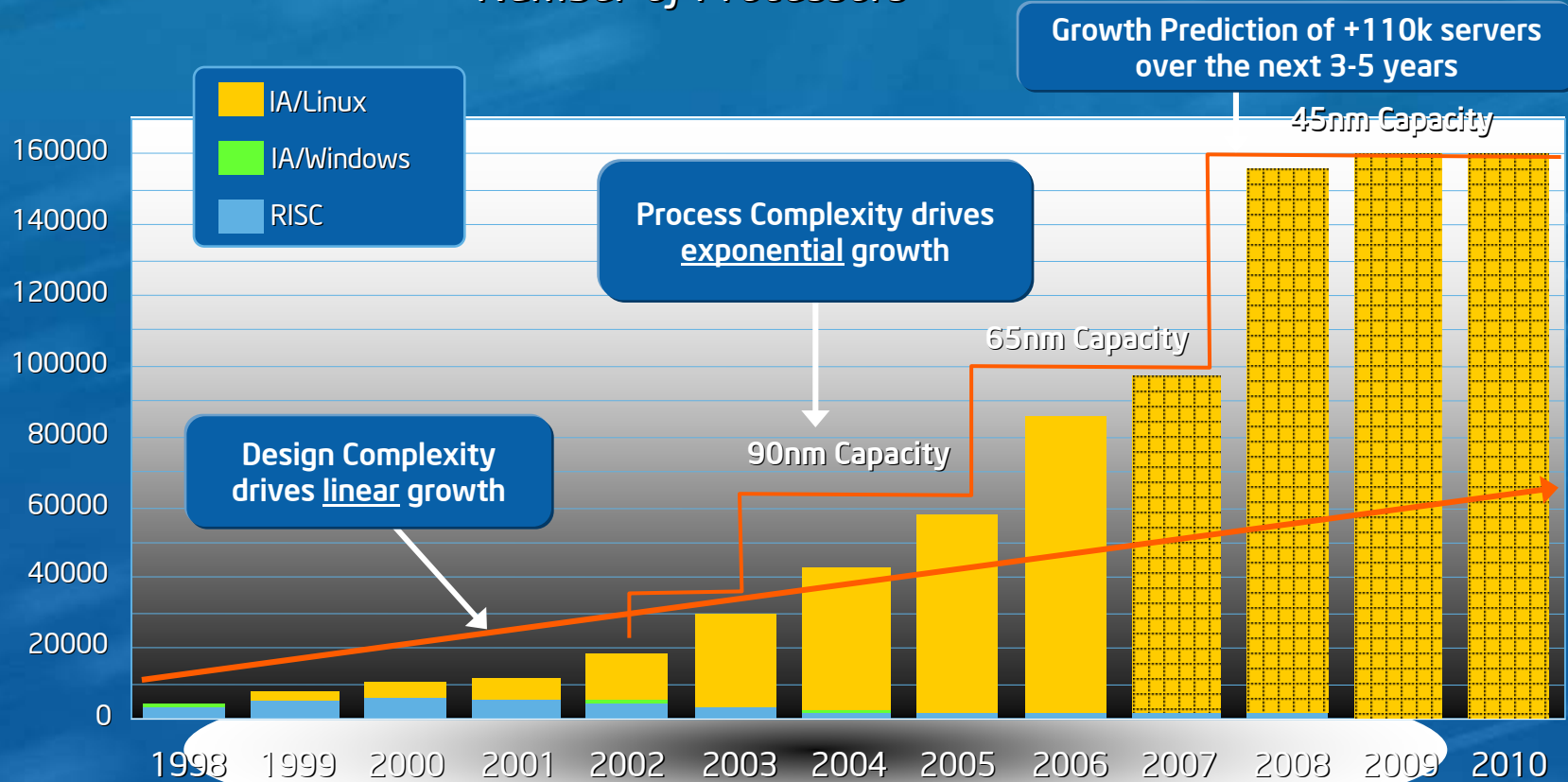


Soft Error: One of Many Challenges

100s & 1000s of Processors

An Example of Datacenter Growth ...

Number of Processors



Compute Capacity Growth is Accelerating

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Source: Intel

*Other names and brands may be claimed as the property of others



Reliable Systems With Unreliable Components

Architectural Techniques

Micro Solutions

Parity
SECCED ECC
 π bit

Macro Solutions

Lockstepping
Redundant multithreading (RMT)
Redundant multi-core CPU

Circuit Techniques

Device Param Tuning

Rad-hard Cell Creation

Process Techniques

State-of-Art Processes

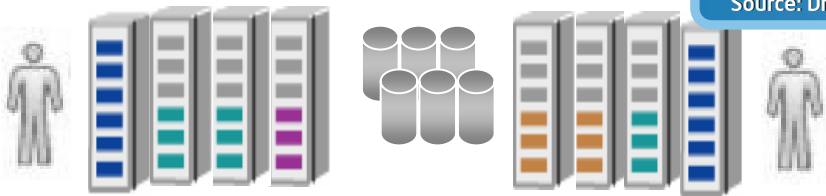
Reducing Single-Bit Soft Errors

Do we need more than Petascale?

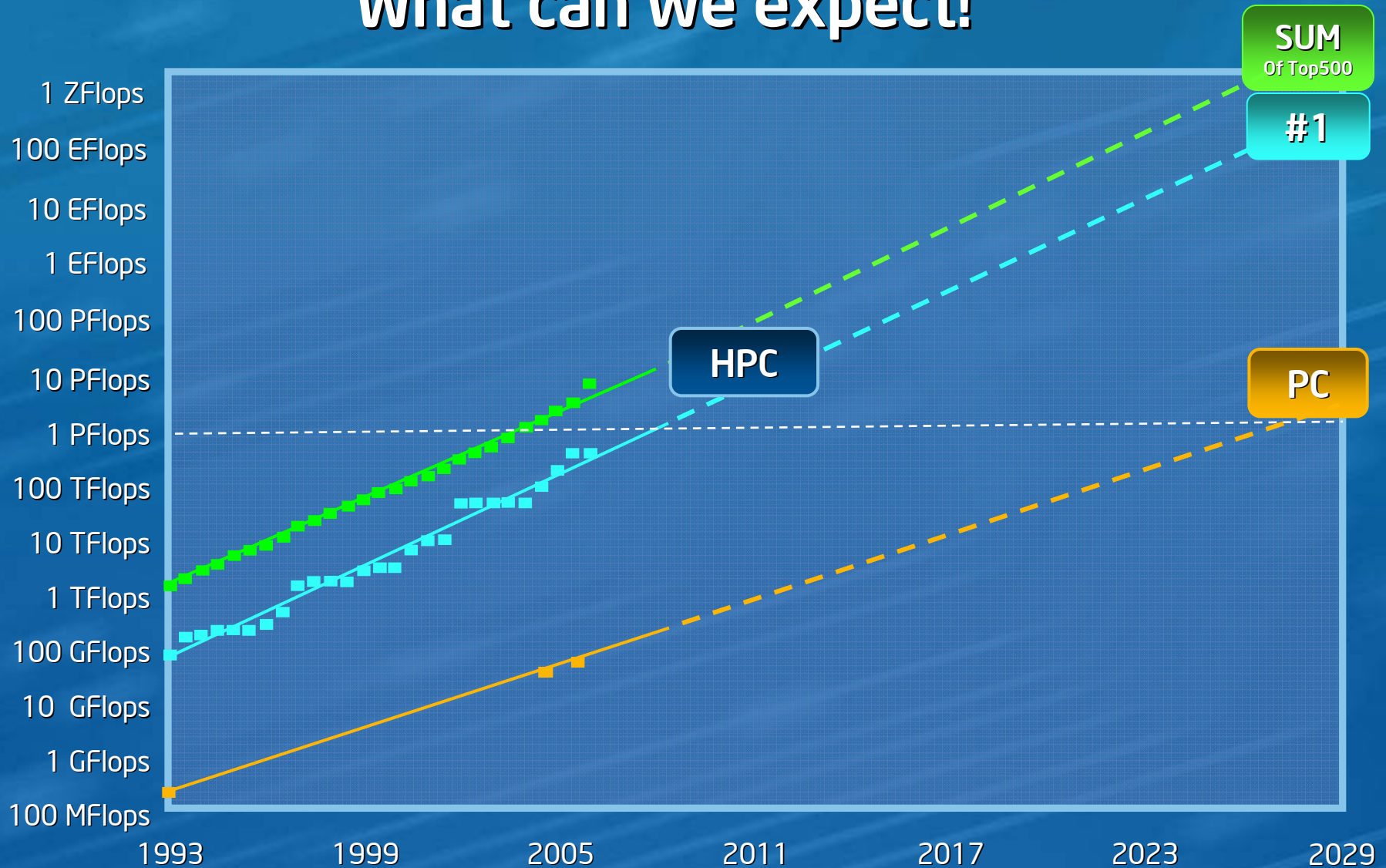
Parallel and programmable
10s to 100s cores and threads
100s and 1000s of processors
100s Gbps chip-to-chip signaling
10s to 100s billions transistors
Dynamic self-test, detect, reconfigure, & adapt

Dynamic Analysis: 1 Petaflops
Laser Optics: 10 Petaflops
Molecular Dynamics in Biology: 20 Petaflops
Aerodynamic Design: 1 Exaflops
Computational Cosmology: 10 Exaflops
Turbulence in Physics: 100 Exaflops
Computational Chemistry: 1 Zettaflops

Source: Dr. Steve Chen, "The Growing HPC Momentum in China", June 30th, 2006, Dresden, Germany



What can we expect!





Q&A



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